appreciated that the bump pad may be integrated into the redistribution layer 254. While a redistribution layer 253 and 254 is shown in both locations in Figure 2F, it is to be appreciated that only one redistribution layer 253 or 254 may be used in some embodiments. In Figures 2E and 2F, various redistribution layers 251-254 are shown. However, it is to be appreciated that embodiments may include any number or combination of redistribution layers 251-254 or redistribution layers in other locations not illustrated in Figures 2E and 2F.

[0047] Referring now to Figure 3A, a plan view illustration of an electronic package 300 is shown, in accordance with an embodiment. In an embodiment, the electronic package 300 comprises an interposer 330 with a plurality of cavities $335_{A\text{-}E.}$ In an embodiment, a plurality of nested components 340 are positioned in the cavities 335. In some embodiments, at least one of the cavities 335 comprises a plurality of nested components 340. For example, two nested components 340 are positioned in cavity 335_B. In an embodiment, the cavities 335 may be entirely within a footprint of a die 320 (indicated by dashed lines), within the footprint of more than one die 320, and/or partially within the footprint of a single die 320. For example, cavities 335_A and 335_B are entirely within a footprint of die 320_A, cavity 335_C is within the footprint of die 320_A and 320_B, cavity 335_E is within the footprint of die 320_A and 320_C, and cavity 335_D is partially within the footprint of die 320_B.

[0048] Referring now to Figure 3B, a cross-sectional schematic illustration of the electronic package 300 in Figure 3A along line B-B' is shown, in accordance with an embodiment. In the illustrated embodiment, the interposer 330 is shown with nested components 340 within cavities 335_A, 335_C, and 335_D. The interposer 330 and the nested components 340 may be electrically coupled to the dies 320_A and 320_B by interconnects

that comprise a layer of bump pads 384. The bump pads 384 are shown schematically between the dies 320_A, 320_B and the interposer 330 and the nested components 340 for simplicity. However, it is to be appreciated that the bump pads 384 may be part of an interconnect substantially similar to the interconnects 181 and 182 described above with respect to Figure 1B. In an embodiment, the bottom surfaces of the interposer 330 and the nested components 340 may be electrically coupled to package side bumps 337.

[0049] Referring now to Figure 3C, a cross-sectional schematic illustration of the electronic package 300 in Figure 3A along line C-C' is shown, in accordance with an embodiment. In the illustrated embodiment, the interposer 330 is shown with nested components 340 within cavities 335_B and 335_E. The interposer 330 and the nested components 340 may be electrically coupled to the dies 320_A and 320_B by interconnects that comprise a layer of bump pads 384. The bump pads 384 are shown schematically between the dies 320_A, 320_B and the interposer 330 and the nested components 340 for simplicity. However, it is to be appreciated that the bump pads 384 may be part of an interconnect substantially similar to the interconnects 181 and 182 described above with respect to Figure 1B. In an embodiment, the bottom surfaces of the interposer 330 and the nested components 340 may be electrically coupled to package side bumps 337.

[0050] Referring now to Figure 4, a plan view illustration of an electronic package 400 is shown, in accordance with an embodiment. In an embodiment, the electronic package 400 may comprise a plurality of interposers $430_{A\text{-}D}$. Each interposer 430 may be any shape. For example, the interposers 430 are illustrated as being rectilinear. The interposers 430 may be arranged so that sidewalls of the interposers 430 define a cavity 435. In an embodiment, one or more nested components 440 may be positioned in the cavity 435. In an embodiment, one or more dies 420 (indicated with